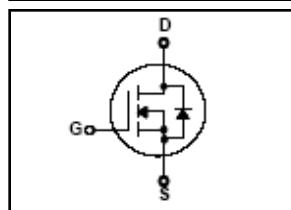


HFS2N65U 650V N-Channel MOSFET

FEATURES

- Originative New Design
- Superior Avalanche Rugged Technology
- Robust Gate Oxide Technology
- Very Low Intrinsic Capacitances
- Excellent Switching Characteristics
- Unrivalled Gate Charge : 5.5 nC (Typ.)
- Extended Safe Operating Area
- Lower $R_{DS(ON)}$: 5 Ω (Typ.) @ $V_{GS}=10V$
- 100% Avalanche Tested

$BV_{DSS} = 650\text{ V}$
 $R_{DS(\text{on}) \text{ typ}} = 5\text{ }\Omega$
 $I_D = 2\text{ A}$



Absolute Maximum Ratings $T_C=25^\circ\text{C}$ unless otherwise specified

Symbol	Parameter	Value	Units
V_{DSS}	Drain-Source Voltage	650	V
I_D	Drain Current – Continuous ($T_C = 25^\circ\text{C}$)	2.0 *	A
	Drain Current – Continuous ($T_C = 100^\circ\text{C}$)	1.3 *	A
I_{DM}	Drain Current – Pulsed (Note 1)	8.0 *	A
V_{GS}	Gate-Source Voltage	± 30	V
E_{AS}	Single Pulsed Avalanche Energy (Note 2)	116	mJ
I_{AR}	Avalanche Current (Note 1)	2.0	A
E_{AR}	Repetitive Avalanche Energy (Note 1)	2.3	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)	4.5	V/ns
P_D	Power Dissipation ($T_C = 25^\circ\text{C}$)	23	W
	- Derate above 25°C	0.18	W/ $^\circ\text{C}$
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to +150	$^\circ\text{C}$
T_L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	300	$^\circ\text{C}$

* Drain current limited by maximum junction temperature

Thermal Resistance Characteristics

Symbol	Parameter	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case	--	5.5	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Junction-to-Ambient	--	62.5	

Package Marking and Ordering Information

Device Marking	Week Marking	Package	Packing	Quantity	RoHS Status
HFS2N65U	YWWX	TO-220F(A)	Tube	50	Pb Free
HFS2N65US	YWWX	TO-220F(B)	Tube	50	Pb Free
HFS2N65U	YWWXg	TO-220F(A)	Tube	50	Halogen Free
HFS2N65US	YWWXg	TO-220F(B)	Tube	50	Halogen Free

* TO-220F(A) : Dual Gauge, TO-220F(B) : Single Gauge

Electrical Characteristics $T_C=25^\circ\text{C}$ unless otherwise specified

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
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On Characteristics

V_{GS}	Gate Threshold Voltage	$V_{DS} = V_{GS}$, $I_D = 250 \mu\text{A}$	2.5	--	4.5	V
$R_{DS(\text{ON})}$	Static Drain-Source On-Resistance	$V_{GS} = 10 \text{ V}$, $I_D = 1.0 \text{ A}$	--	5.0	6.5	Ω

Off Characteristics

BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}$, $I_D = 250 \mu\text{A}$	650	--	--	V
$\Delta BV_{DSS} / \Delta T_J$	Breakdown Voltage Temperature Coefficient	$I_D = 250 \mu\text{A}$, Referenced to 25°C	--	0.6	--	$\text{V}/^\circ\text{C}$
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 650 \text{ V}$, $V_{GS} = 0 \text{ V}$	--	--	1	μA
		$V_{DS} = 520 \text{ V}$, $T_C = 125^\circ\text{C}$	--	--	10	μA
I_{GSS}	Gate-Body Leakage Current	$V_{GS} = \pm 30 \text{ V}$, $V_{DS} = 0 \text{ V}$	--	--	± 100	nA

Dynamic Characteristics

C_{iss}	Input Capacitance	$V_{DS} = 25 \text{ V}$, $V_{GS} = 0 \text{ V}$, $f = 1.0 \text{ MHz}$	--	320	420	pF
C_{oss}	Output Capacitance		--	38	50	pF
C_{rss}	Reverse Transfer Capacitance		--	6.5	8.5	pF

Switching Characteristics

$t_{d(on)}$	Turn-On Time	$V_{DS} = 325 \text{ V}$, $I_D = 2.0 \text{ A}$, $R_G = 25 \Omega$ (Note 4,5)	--	20	50	ns
t_r	Turn-On Rise Time		--	20	50	ns
$t_{d(off)}$	Turn-Off Delay Time		--	30	70	ns
t_f	Turn-Off Fall Time		--	20	50	ns
Q_g	Total Gate Charge	$V_{DS} = 520 \text{ V}$, $I_D = 2.0 \text{ A}$, $V_{GS} = 10 \text{ V}$ (Note 4,5)	--	5.5	7.5	nC
Q_{gs}	Gate-Source Charge		--	1.8	--	nC
Q_{gd}	Gate-Drain Charge		--	3.5	--	nC

Source-Drain Diode Maximum Ratings and Characteristics

I_S	Continuous Source-Drain Diode Forward Current	--	--	2.0	A	
I_{SM}	Pulsed Source-Drain Diode Forward Current	--	--	8.0		
V_{SD}	Source-Drain Diode Forward Voltage	$I_S = 2.0 \text{ A}$, $V_{GS} = 0 \text{ V}$	--	--	1.4	V
trr	Reverse Recovery Time	$I_S = 2.0 \text{ A}$, $V_{GS} = 0 \text{ V}$ $di_F/dt = 100 \text{ A}/\mu\text{s}$ (Note 4)	--	206	--	ns
Qrr	Reverse Recovery Charge		--	0.76	--	μC

Notes :

- Repetitive Rating : Pulse width limited by maximum junction temperature
- $L=53\text{mH}$, $I_{AS}=2\text{A}$, $V_{DD}=50\text{V}$, $R_G=25\Omega$, Starting $T_J=25^\circ\text{C}$
- $I_{SD}\leq 2\text{A}$, $di/dt\leq 200\text{A}/\mu\text{s}$, $V_{DD}\leq BV_{DSS}$, Starting $T_J=25^\circ\text{C}$
- Pulse Test : Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$
- Essentially Independent of Operating Temperature

Typical Characteristics

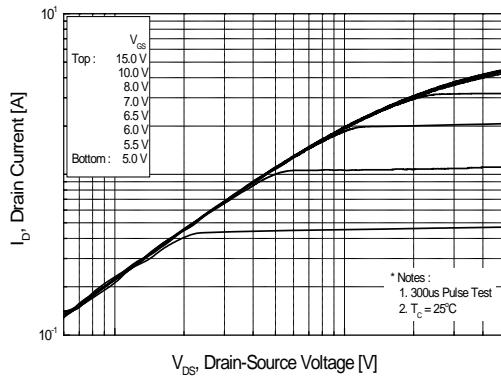


Figure 1. On Region Characteristics

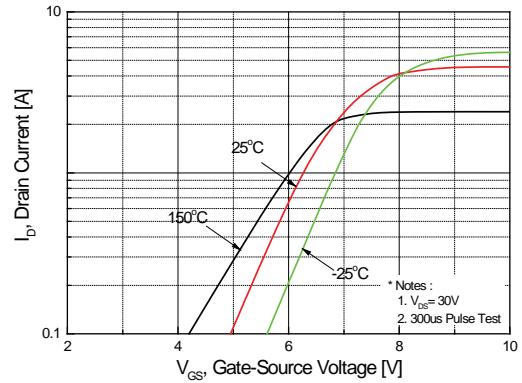


Figure 2. Transfer Characteristics

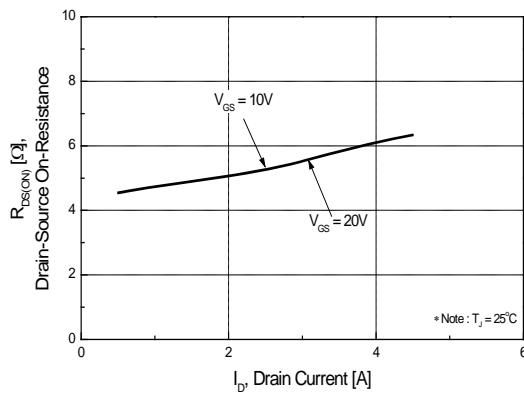


Figure 3. On Resistance Variation vs. Drain Current and Gate Voltage

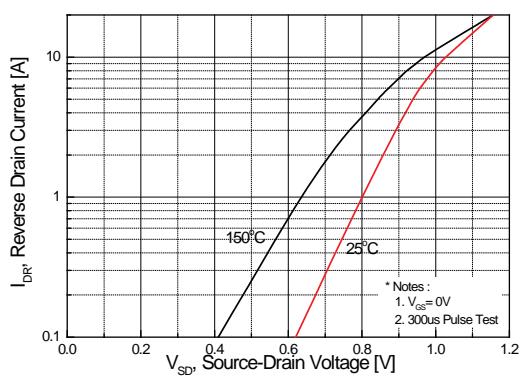


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

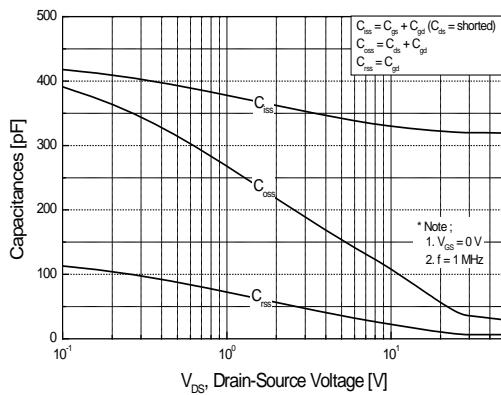


Figure 5. Capacitance Characteristics

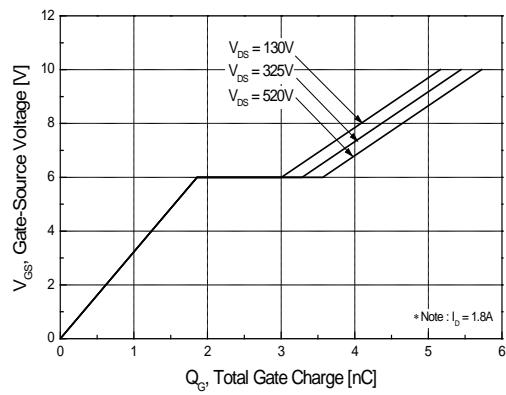


Figure 6. Gate Charge Characteristics

Typical Characteristics (continued)

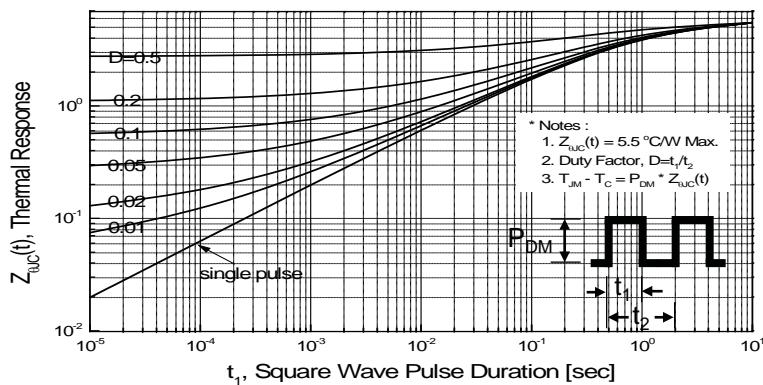
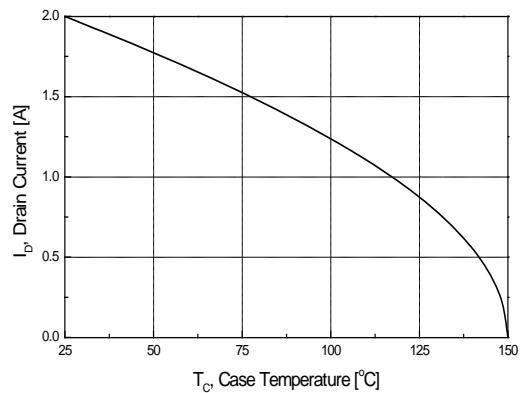
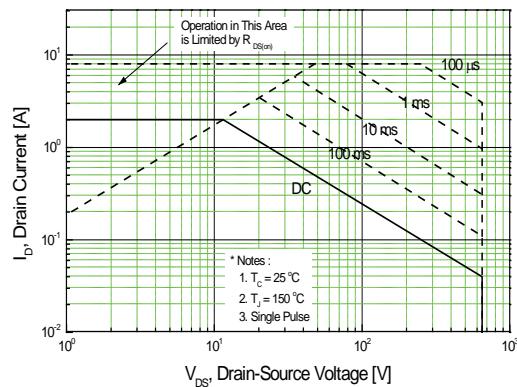
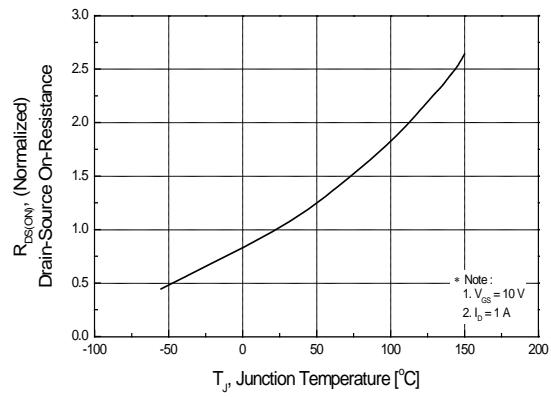
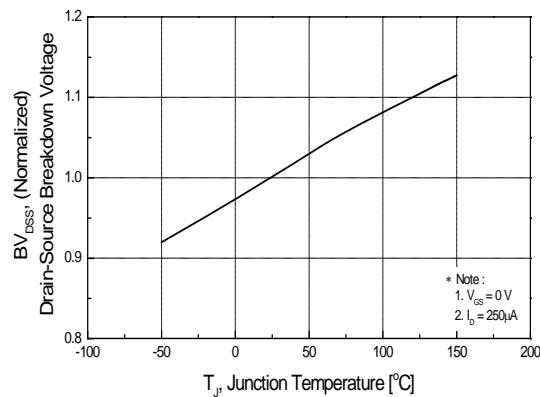


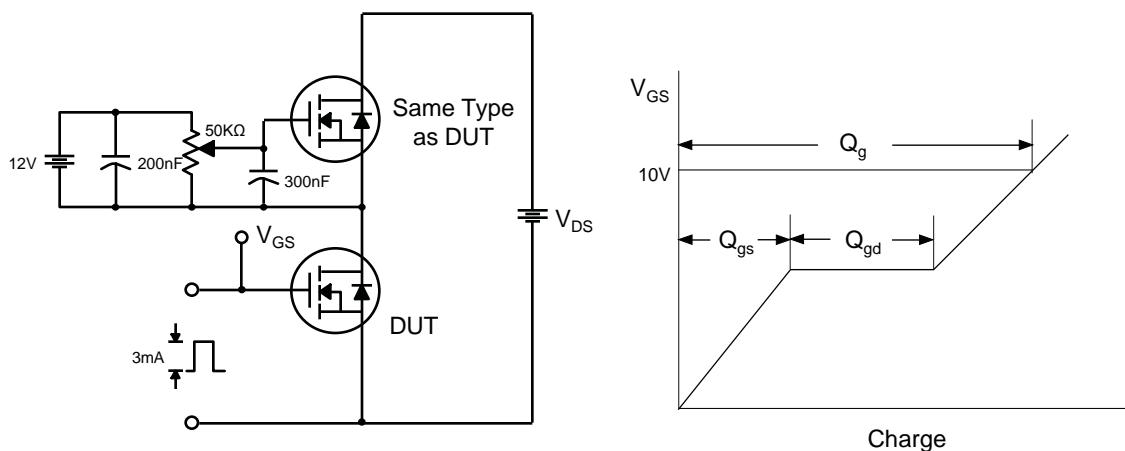
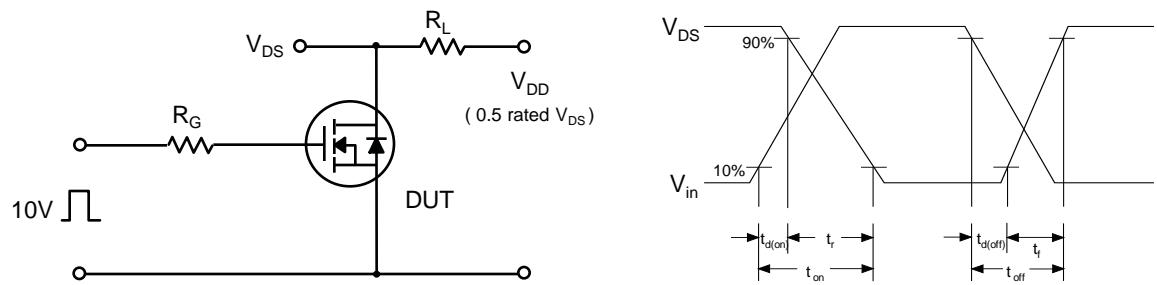
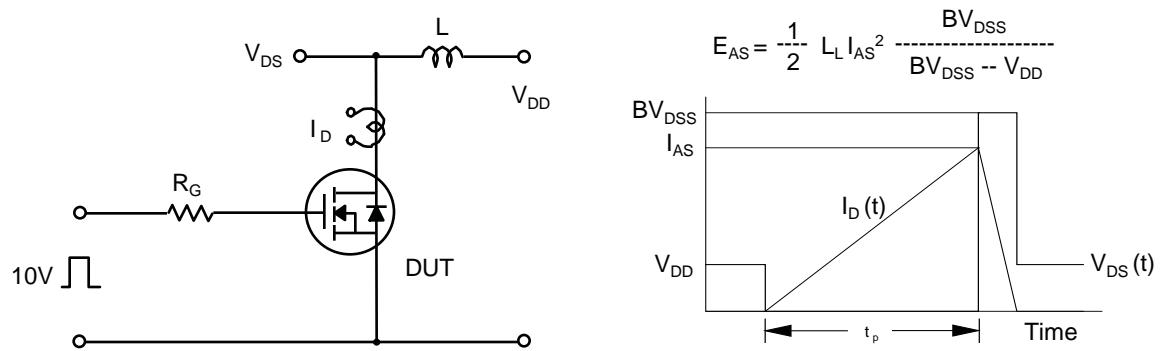
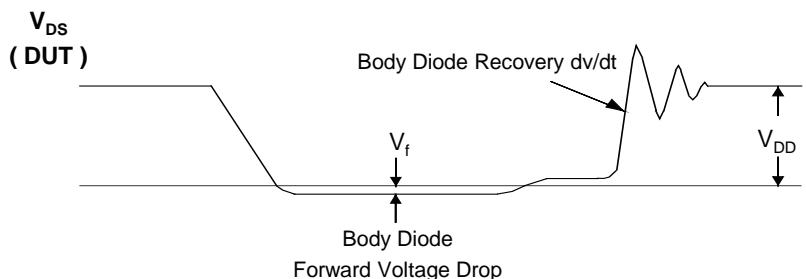
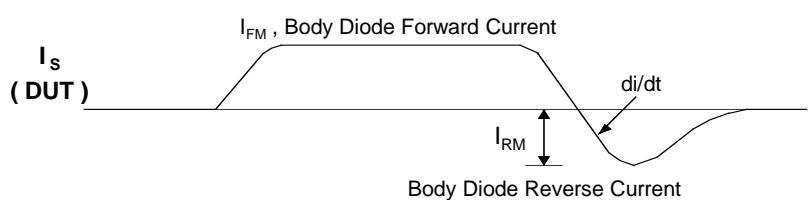
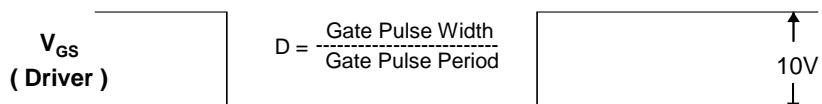
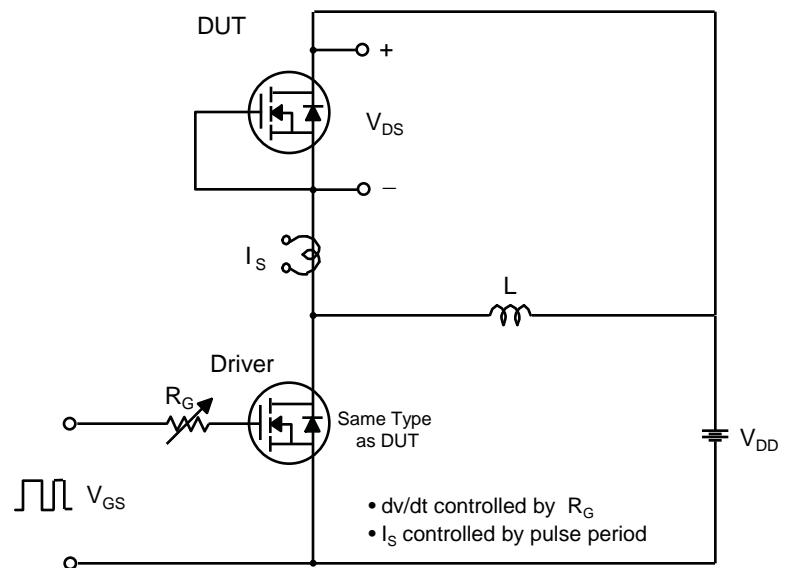
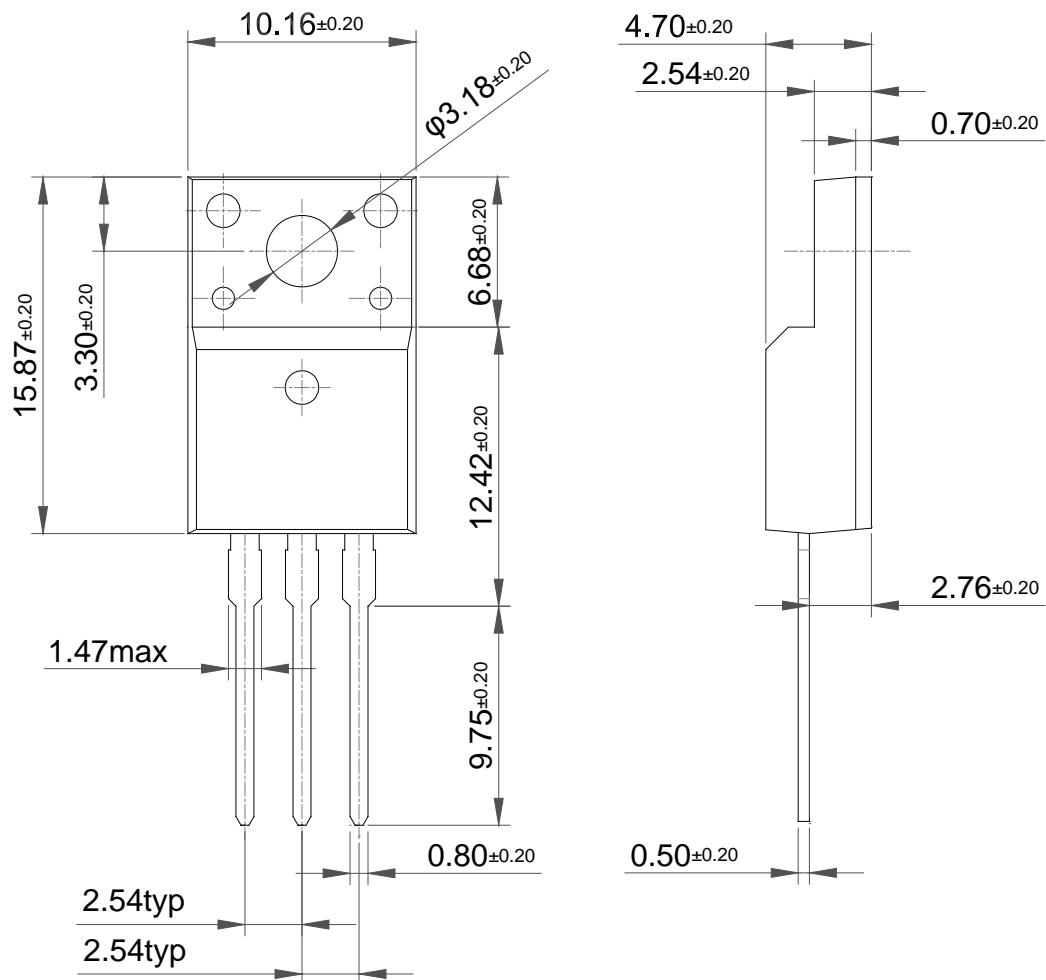
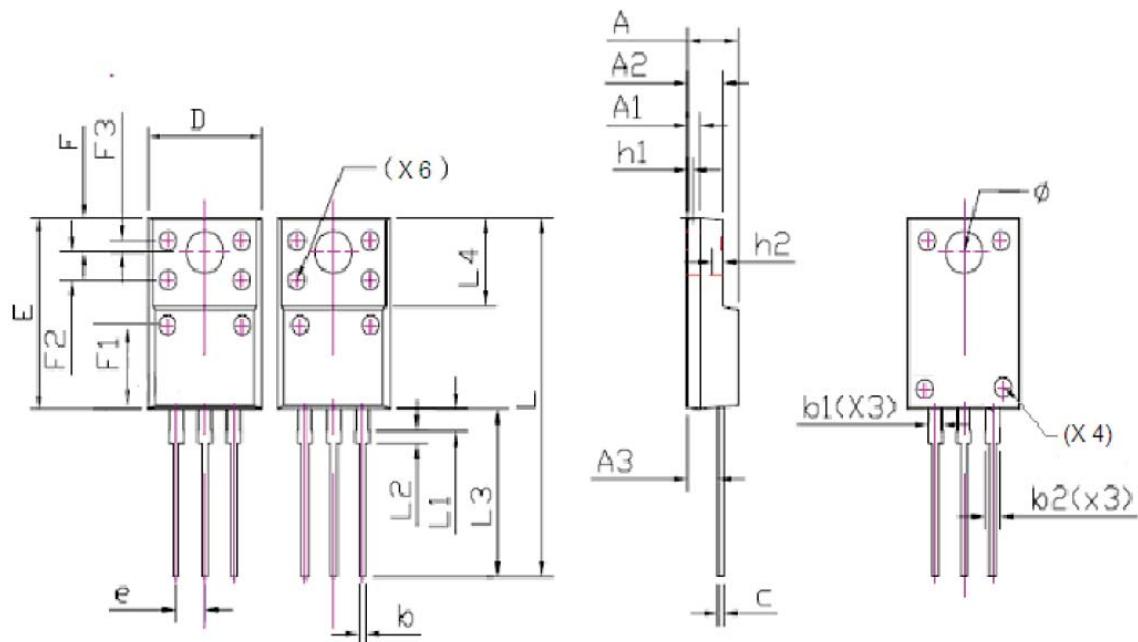
Fig 12. Gate Charge Test Circuit & Waveform**Fig 13. Resistive Switching Test Circuit & Waveforms****Fig 14. Unclamped Inductive Switching Test Circuit & Waveforms**

Fig 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms



Package Dimension**TO-220F (A)**

Package Dimension**TO-220F (B)**

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.300	4.700	0.169	0.185
A1	1.300	REF.	0.051	REF.
A2	2.800	3.300	0.110	0.130
A3	2.500	2.900	0.098	0.114
b	0.500	0.750	0.020	0.030
b1	1.150	1.300	0.045	0.051
b2	1.150	1.400	0.045	0.055
c	0.500	0.750	0.020	0.030
D	9.900	10.360	0.390	0.408
E	14.800	15.200	0.583	0.598
e	2.540	TYP.	0.100	TYP.
F	2.700	REF.	0.106	REF.
F1	6.300	REF.	0.248	REF.
F2	2.200	REF.	0.087	REF.
F3	0.900	REF.	0.035	REF.
Φ	3.200	3.500	0.126	0.138
h1	0.500	REF.	0.020	REF.
h2	0.800	REF.	0.031	REF.
L	28.000	29.000	1.102	1.142
L1	1.400	1.800	0.055	0.071
L2	1.200	2.000	0.047	0.079
L3	13.0	13.8	0.512	0.543
L4	7.000	REF.	0.276	REF.